

**I claim:**

1. An IC package with an implanted heat-dissipation fin, comprising:  
an encapsulant having a PCB side and an opposing open side;  
a chip inside the encapsulant; and  
a heat-dissipation fin implanted in the encapsulant and having a portion thereof extending outside the open side.
2. The IC package with an implanted heat-dissipation fin according to claim 1, wherein said heat-dissipation fin contacts directly with said chip.
3. The IC package with an implanted heat-dissipation fin according to claim 1, wherein said heat-dissipation fin spaces from said chip by a predetermined spacing.
4. The IC package with an implanted heat-dissipation fin according to claim 1, wherein said portion of said heat-dissipation fin further has at least a hookup point.
5. A method for implanting a heat-dissipation fin while packing an IC chip, comprising:  
having a chip encapsulated inside an encapsulant at a melted state;  
before the encapsulant being cured, implanting a heat-dissipation fin into the encapsulant at a predetermined position above the chip and with a portion of the heat-dissipation fin left outside the encapsulant; and  
holding in position the encapsulant and the heat-dissipation fin till the encapsulant being cured.
6. The method for implanting a heat-dissipation fin while packing an IC chip according to claim 5, wherein said predetermined position is a solid

contact state.

7. The method for implanting a heat-dissipation fin while packing an IC chip according to claim 5, wherein said predetermined position is a position with a predetermined spacing.